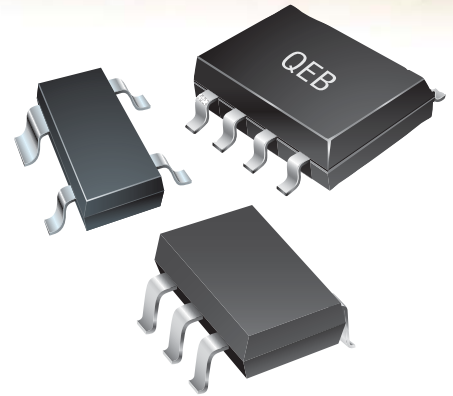


Product Change Notification

CHIP DIODES

Bourns Manufacturers Representatives
 Corporate Distributor Product Managers
 Americas Sales Team
 Asia Sales Team
 Europe Sales Team

July, 2010



Bourns® Diode Products **Addition of Second Wafer Fabrication Location** **and Change to “Green” Compound**

Bourns is adding a second wafer fabrication location, in the UK, for the diode part numbers below to help assure continued secure supply chain management and delivery support to our customers.

Bourns P/N	Bourns P/N
CD143A-SR2.8	CDSOT236-T12C
CD143A-SR3.3	CDSOT236-T15
CDNBS08-SMDA05-6	CDSOT236-T15C
CDSOT236-T05	CDSOT236-T24
CDSOT236-T05C	CDSOT236-T24C
CDSOT236-T12	

Bourns will implement a change to the Green Sumitomo G600 mold compound in the above packages pursuant to our plan to offer more “Green” products to our customers in 2010. Some products can be available in the new “Green” mold compound immediately if requested by customers.

Reliability data, SGS and MDS reports on the units’ package assembly incorporating the above changes will be available on or before August 15, 2010.

Bourns is issuing 90 days notice that mass production from the second wafer fabrication location will be available beginning October 31, 2010. There will be no change in form, fit or function and we do not anticipate any impact to our customers’ applications.